

Stellaris[®] LM3S1911 RevA2 Errata

This document contains known errata at the time of publication for the Stellaris[®] LM3S1911 microcontroller. The table below summarizes the errata and lists the affected revisions. See the data sheet for more details.

See also the ARM[®] Cortex[™]-M3 errata, ARM publication number PR326-PRDC-009450 v2.0.

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1 JTAG and Serial Wire Debug

1.1 JTAG pins do not have internal pull-ups enabled at power-on reset

Description:

Following a power-on reset, the JTAG pins $\overline{\text{TRST}}$, TCK, TMS, TDI, and TDO (PB7 and PC[3:0]) do not have internal pull-ups enabled. Consequently, if these pins are not driven from the board, two things may happen:

- The JTAG port may be held in reset and communication with a four-pin JTAG-based debugger may be intermittent or impossible.
- The receivers may draw excess current.

Workaround:

There are a number of workarounds for this problem, varying in complexity and impact:

1. Add external pull-up resistors to all of the affected pins. This workaround solves both issues of JTAG connectivity and current consumption.
2. Add an external pull-up resistor to $\overline{\text{TRST}}$. Firmware should enable the internal pull-ups on the affected pins by setting the appropriate PUE bits of the appropriate **GPIO Pull-Up Select (GPIOPUR)** registers as early in the reset handler as possible. This workaround addresses the issue of JTAG connectivity, but does not address the current consumption other than to limit the affected period (from power-on reset to code execution).
3. Pull-ups on the JTAG pins are unnecessary for code loaded via the SWD interface or via the serial boot loader. Loaded firmware should enable the internal pull-ups on the affected pins by setting the appropriate PUE bits of the appropriate **GPIOPUR** registers as early in the reset handler as possible. This method does not address the current consumption other than to limit the affected period (from power-on reset to code execution).

Silicon Revision Affected:

A1, A2

2 JTAG

2.1 JTAG INTEST instruction does not work

Description:

The JTAG INTEST (Boundary Scan) instruction does not properly capture data.

Workaround:

None.

Silicon Revision Affected:

A1, A2

3 System Control

3.1 Clock source incorrect when waking up from Deep-Sleep mode in some configurations

Description:

In some clocking configurations, the core prematurely starts executing code before the main oscillator (MOSC) has stabilized after waking up from Deep-Sleep mode. This situation can cause undesirable behavior for operations that are frequency dependent, such as UART communication.

This issue occurs if the system is configured to run off the main oscillator, with the PLL bypassed and the `DSOSCSRC` field of the **Deep-Sleep Clock Configuration (DSLPCCLKCFG)** register set to use the internal 12-MHz oscillator, 30-KHz internal oscillator, or 32-KHz external oscillator. When the system is triggered to wake up, the core should wait for the main oscillator to stabilize before starting to execute code. Instead, the core starts executing code while being clocked from the deep-sleep clock source set in the **DSLPCCLKCFG** register. When the main oscillator stabilizes, the clock to the core is properly switched to run from the main oscillator.

Workaround:

Run the system off of the main oscillator (MOSC) with the PLL enabled. In this mode, the clocks are switched at the proper time.

If the main oscillator must be used to clock the system without the PLL, a simple wait loop at the beginning of the interrupt handler for the wake-up event should be used to stall the frequency-dependent operation until the main oscillator has stabilized.

Silicon Revision Affected:

A1, A2

3.2 PLL may not function properly at default LDO setting

Description:

In designs that enable and use the PLL module, unstable device behavior may occur with the LDO set at its default of 2.5 volts or below (minimum of 2.25 volts). Designs that do not use the PLL module are not affected.

Workaround:

Prior to enabling the PLL module, it is recommended that the default LDO voltage setting of 2.5 V be adjusted to 2.75 V using the **LDO Power Control (LDOPCTL)** register.

Silicon Revision Affected:

A1, A2

3.3 Hard Fault possible when waking from Sleep or Deep-Sleep modes and Cortex-M3 Debug Access Port (DAP) is enabled

Description:

If the Cortex-M3 Debug Access Port (DAP) has been enabled, and the device wakes from a low power sleep or deep-sleep mode, the core may start executing code before all clocks to peripherals have been restored to their run mode configuration. The DAP is usually enabled by software tools

accessing the JTAG or SWD interface when debugging or flash programming. If this condition occurs, a Hard Fault is triggered when software accesses a peripheral with an invalid clock.

Workaround:

A software delay loop can be used at the beginning of the interrupt routine that is used to wake up a system from a WFI (Wait For Interrupt) instruction. This stalls the execution of any code that accesses a peripheral register that might cause a fault. This loop can be removed for production software since the DAP is most likely not enabled during normal execution.

Since the DAP is disabled by default (power on reset), the user can also power cycle the device. The DAP will not be enabled unless it is enabled through the JTAG or SWD interface.

Silicon Revision Affected:

A1, A2

3.4 I/O buffer 5-V tolerance issue

Description:

GPIO buffers are not 5-V tolerant when used in open-drain mode. Pulling up the open-drain pin above 4 V results in high current draw.

Workaround:

When configuring a pin as open drain, limit any pull-up resistor connections to the 3.3-V power rail.

Silicon Revision Affected:

A1, A2

3.5 PLL Runs Fast When Using a 3.6864-MHz Crystal

Description:

If the PLL is enabled, and a 3.6864-MHz crystal is used, the PLL runs 4% fast.

Workaround:

Use a different crystal whose frequency is one of the other allowed crystal frequencies (see the values shown for the XTAL bit in the **RCC** register).

Silicon Revision Affected:

A1, A2

4 Hibernation Module

4.1 Hibernation module WAKE input pin does not work as specified

Description:

The Hibernation module $\overline{\text{WAKE}}$ input pin is used by an external device to trigger a wake-up event and bring the device out of Hibernate mode. This input signal does not behave properly when the device goes into Hibernate mode, and therefore, does not properly wake up the device from hibernation.

Workaround:

The device must be configured to wake up from hibernate mode using the Real-Time-Clock Wake-up by setting the `RTCWEN` bit in the **Hibernation Control (HIBCTL)** register. Disable the External Event Wake-up Enable by clearing the `EXTWEN` bit in the **HIBCTL** register.

Silicon Revision Affected:

A1

4.2 Hibernation module low VBAT detection does not work as expected

Description:

The Hibernation module is designed to detect a low V_{BAT} condition. This feature is enabled by setting the `LOWBATEN` bit in the **Hibernation Control (HIBCTL)** register. When enabled, the low V_{BAT} detection incorrectly detects a low V_{BAT} condition at 3.15 V. This is supposed to trigger a low V_{BAT} condition at 2.35 V.

Workaround:

This feature should not be used and must be disabled by clearing the `LOWBATEN` bit in the **HIBCTL** register. The battery voltage can be sensed using a hardware workaround by wiring an analog comparator input pin to the battery and setting the comparator reference pin voltage to the desired detection trip level.

Silicon Revision Affected:

A1, A2

4.3 Performing a system-wide reset also resets the Hibernation module and all of its registers

Description:

Performing a system-wide reset by asserting the \overline{RST} pin, encountering a Brown-Out Reset, or setting the `SYSRESETREQ` bit in the ARM Cortex-M3 Application Interrupt and Reset Control register also incorrectly causes the Hibernation module to be reset. All of the Hibernation module registers are reset, including the non-volatile **Hibernation Data (HIBDATA)** and the **Hibernation RTC Counter (HIBRTCC)** registers.

Workaround:

None.

Silicon Revision Affected:

A1, A2

4.4 Hibernation module may have higher current draw than specified in data sheet under certain conditions

Description:

If a battery voltage is applied to the V_{BAT} power pin prior to power being applied to the V_{DD} power pins of the device, the current draw from the V_{BAT} pin is greater than expected. The current may be as high as 1.6 mA instead of the data sheet specified 17 μ A. The condition exists until power is applied to the V_{DD} pin. Once the V_{DD} pin has been powered, the V_{BAT} current draw functions as

expected. The VDD pin can then be powered up and down as required and the VBAT pin current specification is maintained.

Workaround:

The VBAT pin higher-than-specified current draw condition can be avoided if the microcontroller's VDD power pins are powered on prior to the time a battery voltage is initially applied to the VBAT pin.

Silicon Revision Affected:

A1, A2

4.5 Hibernation module returns from the Hibernation state to the Wake state regardless of the status of the VDD supply to the microcontroller

Description:

When the Hibernation module is in Hibernation mode and receives an event to initiate a wake-up (assertion of the $\overline{\text{WAKE}}$ pin, RTC match, or low-battery detect), the $\overline{\text{HIB}}$ signal is de-asserted, enabling the external regulator to provide V_{DD} to the device. The device then performs a Power-On Reset (POR) and the software can query the **Hibernation Raw Interrupt Status (HIBRIS)** register to determine if a hibernation wake occurred.

If the regulator does not have a power source, or for some reason V_{DD} is not immediately applied to the device when the $\overline{\text{HIB}}$ signal is de-asserted, the Hibernation module still exits from its Hibernation state to its Wake state, but the device is not able to perform its POR sequence. If power is then restored to the regulator (providing V_{DD} to the device), the device executes a POR, however, the state of the Hibernation module is incorrectly reset, and all of the registers within the Hibernation module, including the **Hibernation RTC Counter (HIBRTCC)** and **Hibernation Data (HIBDATA)** registers are set to their reset state.

Workaround:

Always ensure that power is available to the regulator controlled by the $\overline{\text{HIB}}$ signal when the $\overline{\text{HIB}}$ signal is de-asserted during a wake event.

Silicon Revision Affected:

A1, A2

4.6 Certain Hibernation module register writes cause RTC Counter register inaccuracy

Description:

The Hibernation module contains a **Hibernation RTC Counter (HIBRTCC)** register that keeps an accumulated running one-second count. This register is updated from an internal, 32-KHz counter which is not visible to the user. As this counter value rolls over, it provides a tick count once per second to the **HIBRTCC** register. Register writes to the **Hibernation RTC Match (HIBRTCM0, HIBRTCM1)** registers, the **Hibernation RTC Trim (HIBRTCT)** register, or the **Hibernation Data (HIBDATA)** register cause the 32-KHz counter to reset to its start value. The result is that the **HIBRTCC** register value loses accuracy each time one of these Hibernation registers is written because the 32-KHz counter is reset in the midst of its one-second count window, effectively delaying the **HIBRTCC** register counter value from its ideal value.

Workaround:

To minimize the amount of introduced error, the application can write to the affected registers immediately after the RTC rolls over. The RTC rollover can be detected by polling the RTC value in the **HIBRTCC** register and waiting for it to change. If the application writes to the affected registers with a predictable and repeatable pattern, then the **HIBRTCT** register can be used to compensate for introduced error.

Silicon Revision Affected:

A1, A2

4.7 Hibernation module state retention registers may corrupt after Wake sequence

Description:

When transitioning from a Hibernate condition to a Wake-up state, the **Hibernation Control (HIBCTL)** register and **Hibernation Interrupt Mask (HIBIM)** register values may occasionally become corrupted. This situation occurs after a wake-up event caused by an RTC match condition or an external signal asserting the $\overline{\text{WAKE}}$ pin of the device.

Workaround:

Software should mirror the data in the **HIBCTL** and **HIBIM** registers to the **Hibernation Data (HIBDATA)** register before initiating a Hibernation sequence. Immediately upon returning from the Hibernation state to the Wake-up state, software should write the data mirrored from the **HIBDATA** registers back into the **HIBCTL** and **HIBIM** registers.

Silicon Revision Affected:

A1, A2

5 Flash Controller

5.1 MERASE bit of the FMC register does not erase the entire Flash array

Description:

The **MERASE** bit of the **Flash Memory Control (FMC)** register does not erase the entire Flash array. If the contents of the **Flash Memory Address (FMA)** register contain a value less than 0x20000, only the first 128 KB of the Flash array are erased. If bit 17 (value of 0x20000) is set, then only the upper address range of Flash (greater than 128 KB) is erased.

Workaround:

If the entire array must be erased, the following sequence is recommended:

1. Write a value of 0x00000000 to the **FMA** register.
2. Write a value of 0xA4420004 to the **FMC** register, and poll bit 2 until it is cleared.
3. Write a value of 0x00020000 to the **FMA** register.
4. Write a value of 0xA4420004 to the **FMC** register, and poll bit 2 until it is cleared.

The entire array can also be erased by individually erasing all of the pages in the array.

Silicon Revision Affected:

A1, A2

6 GPIO

6.1 GPIO input pin latches in the Low state if pad type is open drain

Description:

GPIO pins function normally if configured as inputs and the open-drain configuration is disabled. If open drain is enabled while the pin is configured as an input using the **GPIO Alternate Function Select (GPIOAFSEL)**, **GPIO Open Drain Select (GPIOODR)**, and **GPIO Direction (GPIODIR)** registers, then the pin latches Low and excessive current (into pin) results if an attempt is made to drive the pin High. The open-drain device is not controllable.

A GPIO pin is not normally configured as open drain and as an input at the same time. A user may want to do this when driving a signal out of a GPIO open-drain pad while configuring the pad as an input to read data on the same pin being driven by an external device. Bit-banging a bidirectional, open-drain bus (for example, I²C) is an example.

Workaround:

If a user wants to read the state of a GPIO pin on a bidirectional bus that is configured as an open-drain output, the user must first disable the open-drain configuration and then change the direction of the pin to an input. This precaution ensures that the pin is never configured as an input and open drain at the same time.

A second workaround is to use two GPIO pins connected to the same bus signal. The first GPIO pin is configured as an open-drain output, and the second is configured as a standard input. This way the open-drain output can control the state of the signal and the input pin allows the user to read the state of the signal without causing the latch-up condition.

Silicon Revision Affected:

A1, A2

6.2 GPIO pins may glitch during power supply ramp up

Description:

Upon completing a POR (power on reset) sequence, the GPIO pins default to a tri-stated input condition. However, during the initial ramp up of the external V_{DD} supply from 0.0 V to 3.3 V, the GPIO pins are momentarily configured as output drivers during the time the internal LDO circuit is also ramping up. As a result, a signal glitch may occur on GPIO pins before both the external V_{DD} supply and internal LDO voltages reach their normal operating conditions. This situation can occur when the V_{DD} and LDO voltages ramp up at significantly different rates. The LDO voltage ramp-up time is affected by the load capacitance on the LDO pin, therefore, it is important to keep this load at a nominal 1 μ F value as recommended in the data sheet. Adding significant more capacitance loading beyond the specification causes the time delay between the two supply ramp-up times to grow, which possibly increases the severity of the glitching behavior.

Workaround:

Ensuring that the V_{DD} power supply ramp up is as fast as possible helps minimize the potential for GPIO glitches. Follow guidelines for LDO pin capacitive loading documented in the electrical section

of the data sheet. System designers must ensure that, during the V_{DD} supply ramp-up time, possible GPIO pin glitches can cause no adverse effects to their systems..

Silicon Revision Affected:

A1, A2

7 Timers

7.1 General-purpose timer Edge Count mode count error when timer is disabled

Description:

When a general-purpose timer is configured for 16-Bit Input Edge Count Mode, the timer (A or B) erroneously decrements by one when the `Timer Enable (TnEN)` bit in the **GPTM Control (GPTMCTL)** register is cleared (the timer is disabled).

Workaround:

When the general-purpose timer is configured for Edge Count mode and software needs to “stop” the timer, the timer should be reloaded with the current count + 1 and restarted.

Silicon Revision Affected:

A1, A2

7.2 General-purpose timer 16-bit Edge Count mode does not load reload value

Description:

In Edge Count mode, the input events on the `CCP` pin decrement the counter until the count matches what is in the **GPTM Timern Match (GPTMTnMATCHR)** register. At that point, an interrupt is asserted and then the counter should be reloaded with the original value and counting begins again. However, the reload value is not reloaded into the timer.

Workaround:

Rewrite the **GPTM Timern Interval Load (GPTMTnILR)** register before restarting.

Silicon Revision Affected:

A1, A2

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